

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-218 (canceled)

219. (currently amended) A chip package comprising:

a substrate;

only one die having a first top surface at a horizontal level;

an adhesive material joining said substrate and said only one die;

a first insulating layer over said horizontal level, over said only one die, over said substrate and across an edge of said only one die, wherein said first insulating layer comprises a first portion over said only one die and a second portion over said substrate but not over said only one die;

a patterned circuit layer over said first insulating layer, over said horizontal level, over said only one die, ~~and~~ over said substrate and across said edge, wherein said patterned circuit layer is connected to said only one die through a first opening in said first insulating layer;

an inductor over said horizontal level and over said first insulating layer; and

a second insulating layer on said inductor.

220. (previously presented) The chip package of claim 219, wherein said only one die comprises a first trace formed therein, and wherein said patterned circuit layer comprises a second trace having a thickness greater than that of said first trace.

221. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a power bus.

222. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a ground bus.

223. (previously presented) The chip package of claim 219, wherein said patterned circuit layer connects multiple portions of said only one die.

Claims 224-227 (canceled)

228. (previously presented) The chip package of claim 219, wherein said first insulating layer comprises polyimide.

Claims 229-231 (canceled)

232. (previously presented) The chip package of claim 219, wherein said first insulating layer comprises benzocyclobutene (BCB).

Claims 233-235 (canceled)

236. (previously presented) The chip package of claim 219, wherein said adhesive material comprises a conductive paste joining said substrate and said only one die.

Claim 237 (canceled)

238. (previously presented) The chip package of claim 219, wherein said adhesive material comprises an adhesive tape joining said substrate and said only one die.

239. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises an electroplated metal.

240. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises a sputtered metal.

241. (currently amended) The chip package of claim 219, wherein said inductor has a portion vertically directly-over said substrate but not vertically directly-over said only one die.

242. (currently amended) The chip package of claim 219 further comprising a metal bump having a portion vertically directly-over said substrate but not vertically directly-over said only one die.

Claims 243-249 (canceled)

250. (previously presented) The chip package of claim 219, wherein a second opening in said substrate accommodates said only one die.

251. (previously presented) The chip package of claim 250, wherein said substrate has a second top surface substantially coplanar with said first top surface.

252. (previously presented) The chip package of claim 219, wherein said substrate comprises a first layer and a second layer on said first layer, wherein a second opening in said second layer is over said first layer and accommodates said only one die.

253. (previously presented) The chip package of claim 252, wherein said second layer comprises silicon.

254. (previously presented) The chip package of claim 252, wherein said first layer comprises metal.

255. (previously presented) The chip package of claim 252, wherein said second layer has a material different from that of said first layer.

256. (previously presented) The chip package of claim 252, wherein said second layer has a second top surface substantially coplanar with said first top surface and a bottom surface facing said first layer.

257. (previously presented) The chip package of claim 219 further comprising a polymer layer on said substrate, wherein a second opening in said polymer layer is over said substrate and accommodates said only one die.

Claim 258 (canceled)

259. (previously presented) The chip package of claim 257, wherein said polymer layer comprises epoxy.

260. (previously presented) The chip package of claim 219 further comprising a solder bump over said horizontal level.

Claim 261 (canceled)

262. (previously presented) The chip package of claim 219 further comprising a gold bump over said horizontal level.

263. (previously presented) The chip package of claim 219, wherein said only one die comprises multiple active devices, and said patterned circuit layer connects said multiple active devices.

264. (previously presented) The chip package of claim 219, wherein said substrate comprises silicon.

265. (previously presented) The chip package of claim 219, wherein said patterned circuit layer comprises copper.

266. (previously presented) The chip package of claim 219, wherein said substrate comprises metal.

267. (previously presented) The chip package of claim 219, wherein said inductor comprises copper.